MCR106-6, MCR106-8

Preferred Device

Sensitive Gate Silicon Controlled Rectifiers Reverse Blocking Thyristors

PNPN devices designed for high volume consumer applications such as temperature, light and speed control; process and remote control, and warning systems where reliability of operation is important.

- Glass-Passivated Surface for Reliability and Uniformity
- Power Rated at Economical Prices
- Practical Level Triggering and Holding Characteristics
- Flat, Rugged, Thermopad Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Device Marking: Logo, Device Type, e.g., MCR106-6, Date Code

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage ⁽¹⁾ (T _J = -40 to 110°C, Sine Wave 50 to 60 Hz, Gate Open) MCR106–6 MCR106–8	^V drm, ^V rrm	400 600	Volts
On-State RMS Current (T _C = 93°C) (180° Conduction Angles)	IT(RMS)	4.0	Amps
Average On–State Current (180° Conduction Angles; T _C = 93°C)	IT(AV)	2.55	Amps
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 110°C)	ITSM	25	Amps
Circuit Fusing Considerations (t = 8.3 ms)	l ² t	2.6	A ² s
Forward Peak Gate Power $(T_C = 93^{\circ}C, Pulse Width \le 1.0 \mu s)$	PGM	0.5	Watt
Forward Average Gate Power (T _C = 93°C, t = 8.3 ms)	PG(AV)	0.1	Watt
Forward Peak Gate Current $(T_C = 93^{\circ}C, Pulse Width \le 1.0 \mu s)$	IGM	0.2	Amp
Peak Reverse Gate Voltage $(T_C = 93^{\circ}C, Pulse Width \le 1.0 \mu s)$	VRGM	6.0	Volts
Operating Junction Temperature Range	ТJ	-40 to +110	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C
Mounting Torque ⁽²⁾	_	6.0	in. lb.

(1) V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

(2) Torque rating applies with use of compression washer (B52200-F006 or equivalent). Mounting torque in excess of 6 in. lb. does not appreciably lower case-to-sink thermal resistance. Anode lead and heatsink contact pad are common. (See AN209B). For soldering purposes (either terminal connection or device mounting), soldering temperatures shall not exceed +200°C. For optimum results, an activated flux (oxide removing) is recommended.



ON Semiconductor

http://onsemi.com

SCRs 4 AMPERES RMS 400 thru 600 VOLTS





TO-225AA (formerly TO-126) CASE 077 STYLE 2

PIN ASSIGNMENT	
1	Cathode
2	Anode
3	Gate

ORDERING INFORMATION

Device	Package Shippin	
MCR106-6	TO225AA	500/Box
MCR106-8	TO225AA	500/Box

Preferred devices are recommended choices for future use and best overall value.

MCR106-6, MCR106-8

THERMAL CHARACTERISTICS

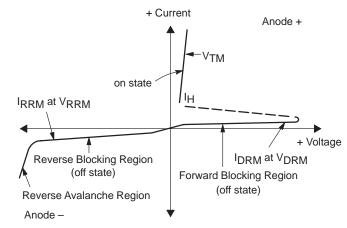
Characteristic		Symbol	Max		Unit	
Thermal Resistance, Junction to Case		R _{θJC}	3.0		°C/W	
Thermal Resistance, Junction to Ambient		R _{θJA}	75		°C/W	
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds		ТL	260		°C	
ELECTRICAL CHARACTERISTICS (T _C = 25°C unless otherwise	e noted.)					
Characteristic	Symbo	ol Mir	п Тур	Max	Unit	
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current $(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM}; R_{GK} = 1000 \text{ Ohms})$ $T_J = 25^{\circ}C$ $T_J = 110^{\circ}C$		RM		10 200	μA μA	
ON CHARACTERISTICS						
Peak Forward On–State Voltage ⁽¹⁾ (I _{TM} = 4 A Peak)	VTM	-	-	2.0	Volts	
Gate Trigger Current (Continuous dc) ⁽²⁾ ($V_{AK} = 7 \text{ Vdc}, R_L = 100 \text{ Ohms}$) ($T_C = -40^{\circ}C$)	lgt	_	_	200 500	μA	
Gate Trigger Voltage (Continuous dc) ⁽²⁾ (V _{AK} = 7 Vdc, R _L = 100 Ohms)	VGT	-	-	1.0	Volts	
Gate Non-Trigger Voltage ⁽²⁾ (V _{AK} = 12 Vdc, R _L = 100 Ohms, T _J = 110°C)	V _{GD}	0.2	· _	-	Volts	
Holding Current (V _{AK} = 7 Vdc, Initiating Current = 200 mA, Gate Open)	Ч			5.0	mA	
DYNAMIC CHARACTERISTICS						
Critical Rate-of-Rise of Off-State Voltage $(T_J = 110^{\circ}C)$	dv/dt	-	10	-	V/µs	

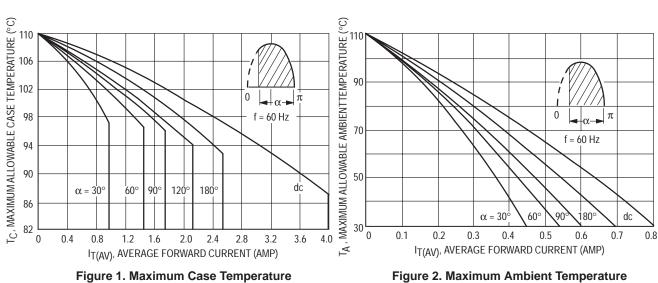
(1) Pulse Test: Pulse Width ≤ 1.0 ms, Duty Cycle ≤ 1%.
(2) R_{GK} current is not included in measurement.

MCR106-6, MCR106-8

Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
IRRM	Peak Reverse Blocking Current
VTM	Peak On State Voltage
Ι _Η	Holding Current

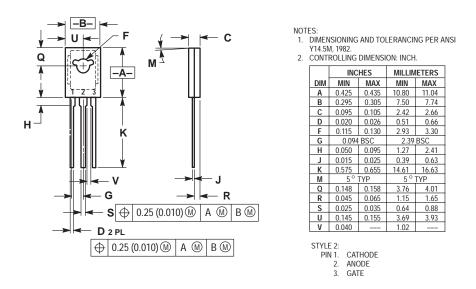




CURRENT DERATING

PACKAGE DIMENSIONS

TO-225AA (formerly TO-126) CASE 077-09 ISSUE W



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